



Integrated Device Technology, Inc.

HIGH-PERFORMANCE CMOS BUS INTERFACE REGISTERS

IDT39C821-26

FEATURES:

- Equivalent to AMD's Am29821-26 Bipolar Registers in pinout/function, speeds and output drive over full temperature and voltage supply extremes
- High-speed parallel registers with positive edge-triggered D-type flip-flops
 - Non-inverting CP-Y $t_{PD} = 7.5ns$ typ.
 - Inverting CP-Y $t_{PD} = 7.5ns$ typ.
- Buffered common Clock Enable (\overline{EN}) and asynchronous Clear input (\overline{CLR})
- 48mA commercial I_{OL} , 32mA military I_{OL}
- 200mV (typ.) hysteresis on clock INPUT
- Clamp diodes on all inputs for ringing suppression
- ESD protection 5000V (typ.) — MIL-STD-883 Category B
- Low input/output capacitance
 - 6pF inputs (typ.)
 - 8pF outputs (typ.)
- CMOS power levels (5 μ W typ. static)
- Both CMOS and TTL output compatible
- Substantially lower input current levels than AMD's Bipolar Am29800 series (5 μ A max.)
- 100% product assurance screening to MIL-STD-883, Class B is available.

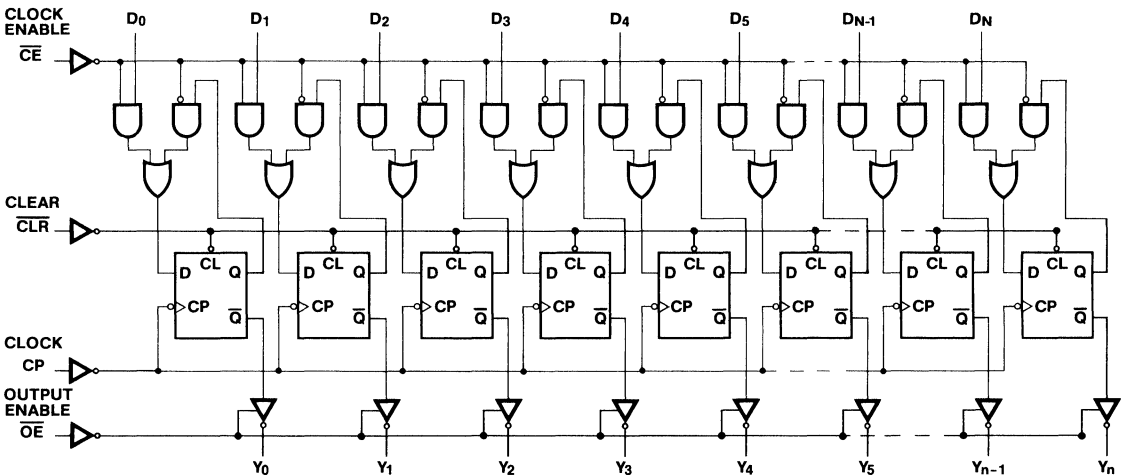
DESCRIPTION:

The IDT39C800 Series is built using advanced CEMOS™, a dual metal CMOS technology.

The IDT39C820 Series bus interface registers are designed to eliminate the extra packages required to buffer existing registers and provide extra data width for wider address/data paths or buses carrying parity. The IDT39C821 and IDT39C822 are buffered, 10-bit wide versions of the popular '374/'534 functions. The IDT39C823 and IDT39C824 are 9-bit wide buffered registers with Clock Enable (\overline{EN}) and Clear (\overline{CLR}) — ideal for parity bus interfacing in high-performance microprogrammed systems. The IDT39C825 and IDT39C826 are 8-bit buffered registers with all the '823/4 controls plus multiple enables ($\overline{OE}_1, \overline{OE}_2, \overline{OE}_3$) to allow multiuser control of the interface, e.g., \overline{CS} , DMA, and RD/ \overline{WR} . They are ideal for use as an output port requiring high I_{OL}/I_{OH} .

All of the IDT39C800 high-performance interface family are designed for high-capacitance load drive capability while providing low-capacitance bus loading at both inputs and outputs. All inputs have clamp diodes, and all outputs are designed for low-capacitance bus loading in the high impedance state.

FUNCTIONAL BLOCK DIAGRAM



SS039C821-001

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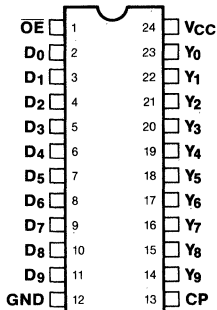
MILITARY AND COMMERCIAL TEMPERATURE RANGES

JULY 1986

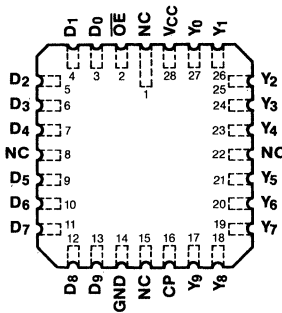
PIN CONFIGURATIONS

LOGIC SYMBOLS

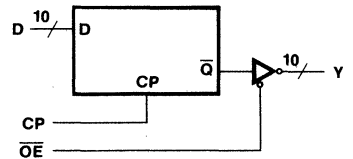
IDT39C821/IDT39C822 10-BIT REGISTERS



SSD39C821-005

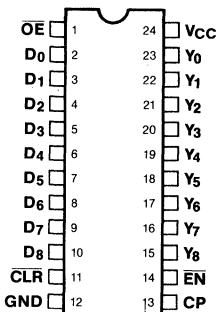


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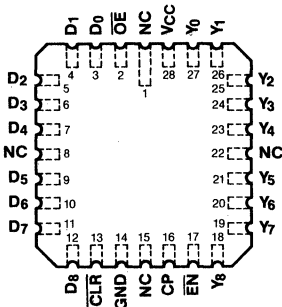


SSD39C821-002

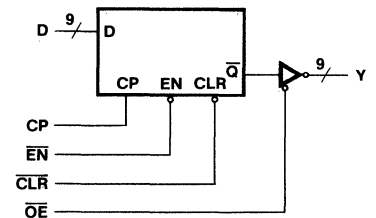
IDT39C823/IDT39C824 9-BIT REGISTERS



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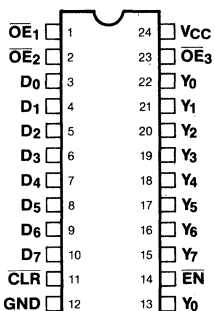


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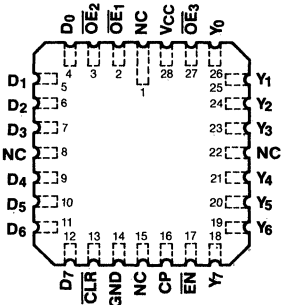


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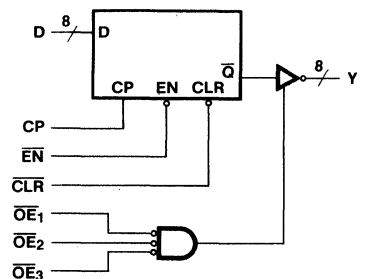
IDT39C825/IDT39C826 8-BIT REGISTERS



SSD39C821-009



SSD39C821-010



SSD39C821-004

PIN DESCRIPTION

NAME	I/O	DESCRIPTION
D _i	I	The D flip-flop data inputs.
$\overline{\text{CLR}}$	I	For both inverting and noninverting registers, when the clear input is LOW and $\overline{\text{OE}}$ is LOW, the Q _i outputs are LOW. When the clear input is HIGH, data can be entered into the register.
CP	I	Clock Pulse for the Register; enters data into the register on the LOW-to-HIGH transition.
Y _i , $\overline{\text{Y}}_i$	O	The register three-state outputs.
$\overline{\text{EN}}$	I	Clock Enable. When the clock enable is LOW, data on the D _i input is transferred to the Q _i output on the LOW-to-HIGH clock transition. When the clock enable is HIGH, the Q _i outputs do not change state, regardless of the data or clock input transitions.
$\overline{\text{OE}}$	I	Output Control. When the $\overline{\text{OE}}$ input is HIGH, the Y _i outputs are in the high impedance state. When the $\overline{\text{OE}}$ input is LOW, the TRUE register data is present at the Y _i outputs.

PRODUCT SELECTOR GUIDE

	DEVICE		
	10-BIT	9-BIT	8-BIT
Noninverting	IDT39C821	IDT39C823	IDT39C825
Inverting	IDT39C822	IDT39C824	IDT39C826

FUNCTION TABLES

IDT39C821/23/25

INPUTS					INTERNAL OUTPUTS		FUNCTION
$\overline{\text{OE}}$	$\overline{\text{CLR}}$	$\overline{\text{EN}}$	D _i	CP	Q _i	Y _i	
H	X	L	L	↑	L	Z	Hi-Z
H	X	L	H	↑	H	Z	
H	L	X	X	X	L	Z	Clear
L	L	X	X	X	L	L	
H	H	H	X	X	NC	Z	Hold
L	H	H	X	X	NC	NC	
H	H	L	L	↑	L	Z	Load
H	H	L	H	↑	H	Z	
L	H	L	L	↑	L	L	
L	H	L	H	↑	H	H	

H = HIGH
 L = LOW
 X = Don't Care
 NC = No Change
 ↑ = LOW-to-HIGH Transition
 Z = High Impedance

IDT39C822/24/26

INPUTS					INTERNAL OUTPUTS		FUNCTION
$\overline{\text{OE}}$	$\overline{\text{CLR}}$	$\overline{\text{EN}}$	D _i	CP	Q _i	$\overline{\text{Y}}_i$	
H	X	L	L	↑	H	Z	Hi-Z
H	X	L	H	↑	L	Z	
H	L	X	X	X	L	Z	Clear
L	L	X	X	X	L	L	
H	H	H	X	X	NC	Z	Hold
L	H	H	X	X	NC	NC	
H	H	L	L	↑	H	Z	Load
H	H	L	H	↑	L	Z	
L	H	L	L	↑	H	H	
L	H	L	H	↑	L	L	

H = HIGH
 L = LOW
 X = Don't Care
 NC = No Change
 ↑ = LOW-to-HIGH Transition
 Z = High Impedance

ABSOLUTE MAXIMUM RATING⁽¹⁾

SYMBOL	RATING	COMMERCIAL	MILITARY	UNIT
V _{TERM}	Terminal Voltage with Respect to GND	-0.5 to +7.0	-0.5 to +7.0	V
T _A	Operating Temperature	0 to +70	-55 to +125	°C
T _{BIAS}	Temperature Under Bias	-55 to +125	-65 to +135	°C
T _{STG}	Storage Temperature	-55 to +125	-65 to +155	°C
I _{OUT}	DC Output Current	100	100	mA

NOTE:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

CAPACITANCE (T_A = +25°C, f = 1.0MHz)

SYMBOL	PARAMETER ⁽¹⁾	CONDITIONS	TYP.	UNIT
C _{IN}	Input Capacitance	V _{IN} = 0V	6	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0V	8	pF

NOTE:

- This parameter is sampled and not 100% tested.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

T _A = 0°C to +70°C	V _{CC} = 5.0V ± 5%	Min. = 4.75V	Max. = 5.25V (Commercial)
T _A = -55°C to +125°C	V _{CC} = 5.0V ± 10%	Min. = 4.50V	Max. = 5.50V (Military)
V _{LC} = 0.2V			
V _{HC} = V _{CC} - 0.2V			

SYMBOL	PARAMETER	TEST CONDITIONS ⁽¹⁾	MIN.	TYP. ⁽²⁾	MAX.	UNIT	
V _{IH}	Input HIGH Level	Guaranteed Logic High Level	2.0	—	—	V	
V _{IL}	Input LOW Level	Guaranteed Logic Low Level	—	—	0.8	V	
I _{IH}	Input HIGH Current	V _{CC} = Max., V _{IN} = V _{CC}	—	—	5	μA	
I _{IL}	Input LOW Current	V _{CC} = Max., V _{IN} = GND	—	—	-5	μA	
V _I	Clamp Diode Voltage	V _{CC} = Min., I _N = -18mA	—	-0.7	-1.2	V	
I _{OZ}	Off State (High Impedance) Output Current	V _{CC} = Max.					
		V _O = 0.4V	—	—	-10	μA	
		V _O = 2.4V	—	—	10		
I _{SC}	Short Circuit Current	V _{CC} = Max. ⁽³⁾	-75	-120	—	mA	
V _{OH}	Output HIGH Voltage	V _{CC} = 3V, V _{IN} = V _{LC} or V _{HC} , I _{OH} = -32μA	V _{HC}	V _{CC}	—	V	
		V _{CC} = Min. V _{IN} = V _{IH} or V _{IL}	I _{OH} = -250μA	V _{HC}	V _{CC}		—
			I _{OH} = -15mA MIL.	2.4	4.0		—
		I _{OH} = -24mA COM.	2.0	3.5	—		
V _{OL}	Output LOW Voltage	V _{CC} = 3V, V _{IN} = V _{LC} or V _{HC} , I _{OL} = 300μA	—	GND	V _{LC}	V	
		V _{CC} = Min. V _{IN} = V _{IH} or V _{IL}	I _{OL} = 300μA	—	GND		V _{LC}
			I _{OL} = 32mA MIL.	—	—		0.5
		I _{OL} = 48mA COM.	—	—	0.5		
V _H	Input Hysteresis on Clock Only	—	—	200	—	mV	

NOTES:

- For conditions shown as max. or min., use appropriate value specified under Electrical Characteristics for the applicable device type.
- Typical values are at V_{CC} = 5.0V, +25°C ambient and maximum loading.
- Not more than one output should be shorted at one time. Duration of the short circuit test should not exceed one second.

POWER SUPPLY CHARACTERISTICS

$$V_{LC} = 0.2V; V_{HC} = V_{CC} - 0.2V$$

SYMBOL	PARAMETER	TEST CONDITIONS ⁽¹⁾		MIN.	TYP. ⁽²⁾	MAX.	UNIT
I_{CCQ}	Quiescent Power Supply Current	$V_{CC} = \text{Max.}$ $V_{IN} \geq V_{HC}; V_{IN} \leq V_{LC}$ $f_{CP} = f_i = 0$		—	0.001	1.5	mA
I_{CCT}	Quiescent Power Supply Current TTL Inputs HIGH	$V_{CC} = \text{Max.}$ $V_{IN} = 3.4V^{(3)}$		—	0.5	1.6	mA
I_{CCD}	Dynamic Power Supply Current	$V_{CC} = \text{Max.}$ Outputs Open OE = GND One Bit Toggling 50% Duty Cycle	$V_{IN} \geq V_{HC}$ $V_{IN} \leq V_{LC}$	—	0.15	0.25	mA/ MHz
I_{CC}	Total Power Supply ⁽⁴⁾ Current	$V_{CC} = \text{Max.}$ Outputs Open $f_{CP} = 10\text{MHz}$ 50% Duty Cycle OE = GND One Bit Toggling at $f_i = 5\text{MHz}$ 50% Duty Cycle	$V_{IN} \geq V_{HC}$ $V_{IN} \leq V_{LC}$ (FCT)	—	1.5	4.0	mA
		$V_{CC} = \text{Max.}$ Outputs Open $f_{CP} = 10\text{MHz}$ 50% Duty Cycle OE = GND Eight Bits Toggling at $f_i = 2.5\text{MHz}$ 50% Duty Cycle	$V_{IN} = 3.4V$ or $V_{IN} = \text{GND}$	—	2.0	5.6	
		$V_{CC} = \text{Max.}$ Outputs Open $f_{CP} = 10\text{MHz}$ 50% Duty Cycle OE = GND	$V_{IN} \geq V_{HC}$ $V_{IN} \leq V_{LC}$ (FCT)	—	3.75	7.8	
		$V_{CC} = \text{Max.}$ Outputs Open $f_{CP} = 10\text{MHz}$ 50% Duty Cycle OE = GND Eight Bits Toggling at $f_i = 2.5\text{MHz}$ 50% Duty Cycle	$V_{IN} = 3.4V$ or $V_{IN} = \text{GND}$	—	6.0	15.0	

NOTES:

1. For conditions shown as max. or min., use appropriate value specified under Electrical Characteristics for the applicable device type.

2. Typical values are at $V_{CC} = 5.0V$, +25°C ambient and maximum loading.

3. Per TTL driven input ($V_{IN} = 3.4V$); all other inputs at V_{CC} or GND.

$$4. I_{CC} = I_{\text{QUIESCENT}} + I_{\text{INPUTS}} + I_{\text{DYNAMIC}}$$

$$I_{CC} = I_{CCQ} + I_{CCT}D_HN_T + I_{CCD}(f_{CP}/2 + f_iN_i)$$

$$I_{CCQ} = \text{Quiescent Current}$$

$$I_{CCT} = \text{Power Supply Current for a TTL High Input } (V_{IN} = 3.4V)$$

$$D_H = \text{Duty Cycle for TTL Inputs High}$$

$$N_T = \text{Number of TTL Inputs at } D_H$$

$$I_{CCD} = \text{Dynamic Current caused by an Input Transition pair (HLH or LHL)}$$

$$f_{CP} = \text{Clock Frequency for Register Devices (Zero for Non-Register Devices)}$$

$$f_i = \text{Input Frequency}$$

$$N_i = \text{Number of Inputs at } f_i$$

All currents are in milliamps and all frequencies are in megahertz.

SWITCHING CHARACTERISTICS OVER OPERATING RANGE

PARAMETERS	DESCRIPTION	TEST CONDITIONS ⁽¹⁾	COMMERCIAL		MILITARY		UNITS
			MIN.	MAX.	MIN.	MAX.	
t_{PLH} t_{PHL}	Propagation Delay Clock to Y_i ($\overline{OE} = \text{LOW}$)	$C_L = 50\text{pF}$ $R_L = 500\Omega$	—	12	—	12	ns
t_{PLH} t_{PHL}		$C_L = 300\text{pF}$ $R_L = 500\Omega$	—	20	—	20	ns
t_S	Data to CP Setup Time	$C_L = 50\text{pF}$ $R_L = 500\Omega$	4		4		ns
t_H	Data to CP Hold Time		2		2		ns
t_S	Enable ($\overline{EN} \downarrow$) to CP Setup Time		4		4		ns
t_S	Enable ($\overline{EN} \uparrow$) to CP Setup Time		4		4		ns
t_H	Enable (\overline{EN}) Hold Time		2		2		ns
t_{PHL}	Propagation Delay, Clear to Y_i			20		20	ns
t_S	Clear Recovery ($\overline{CLR} \downarrow$) Time			7		7	ns
t_{PWH}	Clock Pulse Width		HIGH	7		7	ns
t_{PWL}			LOW	7		7	ns
t_{PWL}	Clear ($\overline{CLR} = \text{LOW}$) Pulse Width			7		7	ns
t_{ZH} t_{ZL}	Output Enable Time $\overline{OE} \downarrow$ to Y_i	$C_L = 300\text{pF}$ $R_L = 500\Omega$		23		25	ns
t_{ZH} t_{ZL}		$C_L = 50\text{pF}$ $R_L = 500\Omega$		14		15	ns
t_{HZ} t_{LZ}	Output Disable Time $\overline{OE} \uparrow$ to Y_i	$C_L = 50\text{pF}$ $R_L = 500\Omega$		16		18	ns
$t_{HZ}^{(2)}$ t_{LZ}		$C_L = 5\text{pF}$ $R_L = 500\Omega$		9		10	ns

NOTE:

1. See test circuit and waveforms.
2. This parameter guaranteed but not tested.